

STH250N55F3-6

N-channel 55 V, 2.2 mΩ, 180 A, H²PAK STripFET™ III Power MOSFET

Features

Order code	V _{DSS}	R _{DS(on)} max.	Ι _D	Pw
STH250N55F3-6	55 V	$2.6 \text{ m}\Omega$	180 A ⁽¹⁾	300 W

- 1. Value limited by package
- Ultra low on-resistance
- 100% avalanche tested

Application

Switching applications

Description

This N-channel STripFET™ III Power MOSFET technology is among the latest improvements, which have been especially tailored to minimize on-state resistance providing superior switching performance.

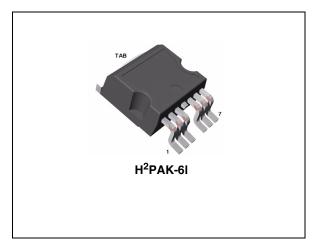


Figure 1. Internal schematic diagram

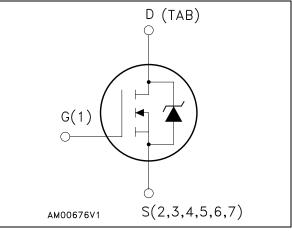


Table 1.Device summary

Order code	Marking	Package	Packaging
STH250N55F3-6	250N55F3	H ² PAK	Tape and reel

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Electrical ratings

Table 2.	Absolute	maximum	ratings
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Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage (V _{GS} =0)	55	V
V _{GS}	Gate-source voltage	± 20	V
I _D ⁽¹⁾	Drain current (continuous) at $T_C = 25 \ ^{\circ}C$	180	А
I _D ⁽¹⁾	Drain current (continuous) at T _C =100 °C	160	А
I _{DM} ⁽²⁾	Drain current (pulsed)	720	А
P _{TOT}	Total dissipation at $T_C = 25 \ ^{\circ}C$	300	W
	Derating factor	2.0	W/°C
dv/dt ⁽³⁾	Peak diode recovery voltage slope	11	V/ns
E _{AS} ⁽⁴⁾	Single pulse avalanche energy	1000	mJ
T _j T _{stg}	Operating junction temperature storage temperature	- 55 to 175	°C

1. Current limited by package.

2. Pulse width limited by safe operating area.

3. I_{SD} $\leq\!\!120$ A, di/dt $\leq\!900$ A/µs, V_{DD} $\leq\!V_{(BR)DSS},$ T_{J} $\leq\!T_{JMAX}$

4. Starting Tj = 25 °C, I_D = 60 A, V_{DD} = 40 V (see Figure 16 and Figure 17)

	Table 3	3. T	herm	nal e	data
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Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	0.5	°C/W
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-ambient max	35	°C/W

1. When mounted on FR-4 board, on 1inch², 2oz Cu.



2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	55			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = max rating, V _{DS} = max rating,@125°C			10 100	μΑ μΑ
I _{GSS}	Gate body leakage current (V _{DS} = 0)	$V_{GS} = \pm 20 V$			±200	nA
V _{GS(th)}	Gate threshold voltage	V_{DS} = V_{GS} , I_D = 250 μ A	2		4	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 , I _D = 60 A		2.2	2.6	mΩ

Table 4. On/off states

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25 V, f = 1 MHz, V _{GS} = 0	-	6800 1450 15	-	pF pF pF
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 27.5 \text{ V}, \text{ I}_{D} = 60 \text{ A}$ $R_{G} = 4.7 \Omega V_{GS} = 10 \text{ V}$ (see Figure 13, Figure 18)	-	25 150 110 50	-	ns ns ns ns
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 44 \text{ V}, I_D = 120 \text{ A},$ $V_{GS} = 10 \text{ V},$ (see <i>Figure 14</i>)	-	100 30 26	-	nC nC nC



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} ⁽¹⁾	Source-drain current Source-drain current (pulsed)		-		180 720	A A
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} =120 A, V _{GS} =0	-		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _{SD} =120 A, di/dt = 100 A/μs, V _{DD} = 35 V, Tj=150 °C (see <i>Figure 15</i>)	-	60 0.11 3.5		ns μC Α

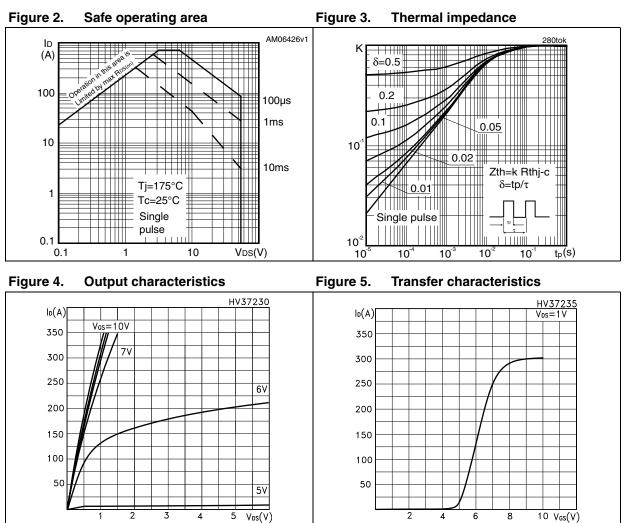
Table 6.Source drain diode

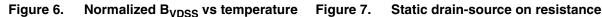
1. Pulse width limited by safe operating area

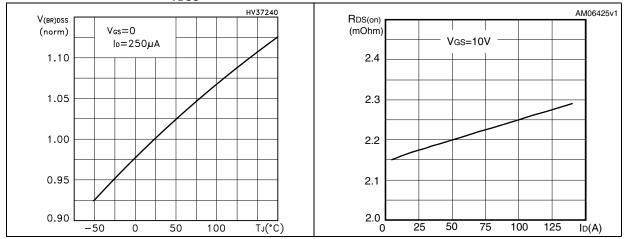
2. Pulsed: pulse duration = $300\mu s$, duty cycle 1.5%



2.1 Electrical characteristics (curves)









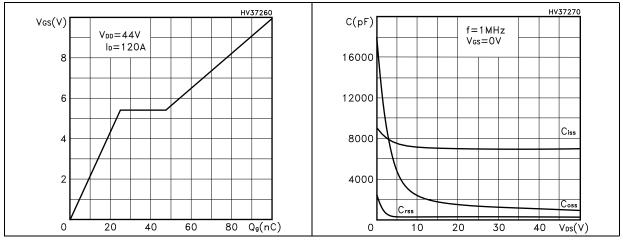


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

Figure 10. Normalized gate threshold voltage Figure 11. Normalized on resistance vs vs temperature temperature

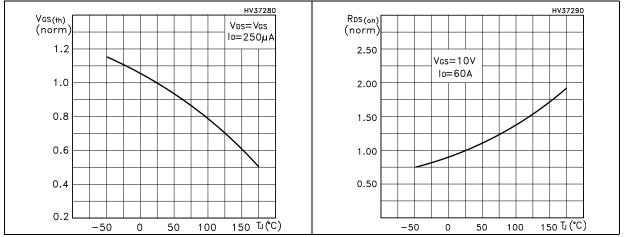
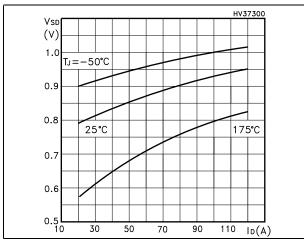
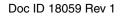


Figure 12. Source-drain diode forward characteristics

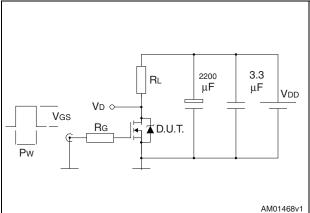


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3 Test circuits

Figure 13. Switching times test circuit for resistive load



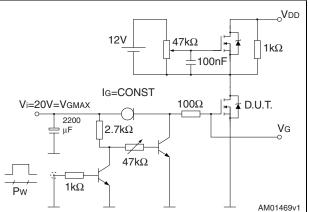
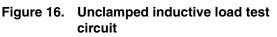
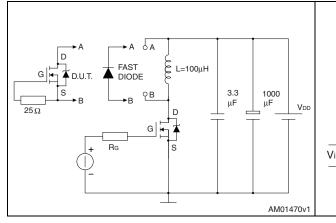
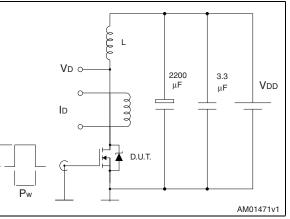


Figure 14. Gate charge test circuit

Figure 15. Test circuit for inductive load switching and diode recovery times







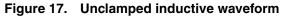
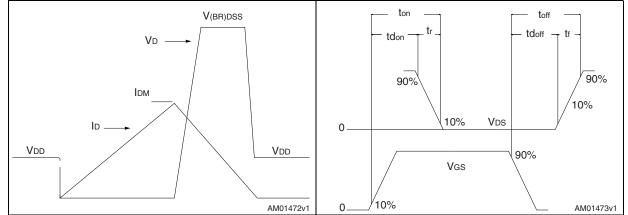


Figure 18. Switching time waveform



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4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Dim.	mm				
Dim.	Min.	Тур.	Max.		
A	4.30		4.80		
A1	0.03		0.20		
С	1.17		1.37		
е	2.34		2.74		
e1	4.88		5.28		
e2	7.42		7.82		
E	0.45	-	0.60		
F	0.50	-	0.70		
Н	10.00		10.40		
H1	7.80		8.20		
L	14.75		15.25		
L1	1.27		1.40		
L2	4.35		4.95		
L3	7.45		7.85		
L4	1.5]	1.75		
М	1.90	1	2.50		
R	0.20	1	0.60		
V	0°]	8°		

 Table 7.
 H²PAK-6 mechanical data



Figure 19. H²PAK-6 drawing

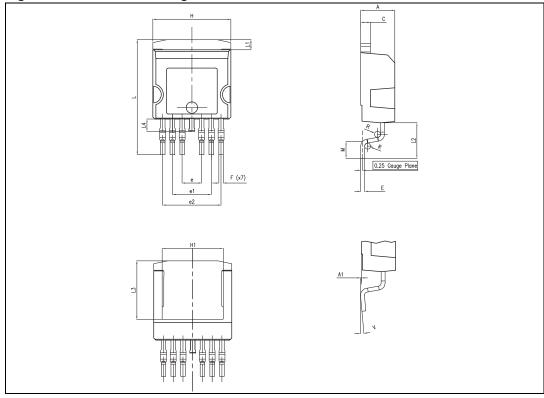
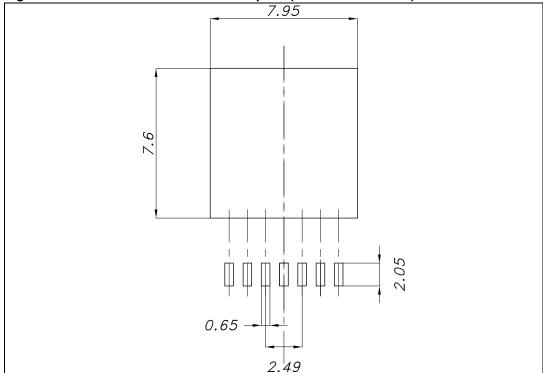


Figure 20. H²PAK-6 recommended footprint (dimensions in mm)





5 Packaging mechanical data

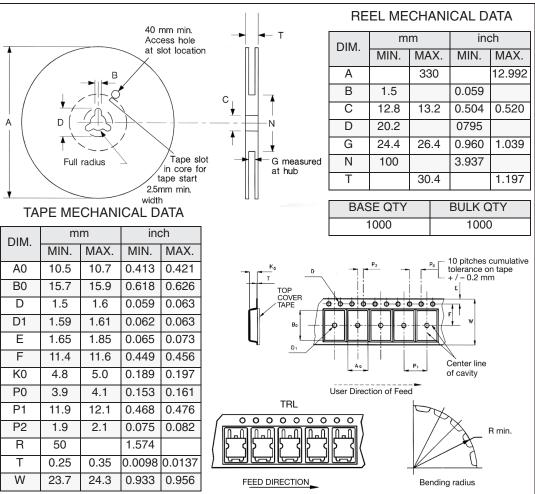


Figure 21. H²PAK-6 tape and reel



6 Revision history

Date	Revision	Changes
01-Oct-2010	1	First release



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